

In the claims:

Please amend the claims in the following manner:

1-18. (cancelled)

19. (currently amended) A method of assembling a multi-chip device comprising:
populating a second surface of an interposer having a first surface and the second
surface with a plurality of conductive pads;
coupling solder balls only to selected ones of the plurality of conductive pads that are
intended to be used, said selected ones being less than all the plurality of conductive pads;
~~not coupling the solder balls to non-selected ones of the plurality of conductive~~
~~pads, said non-selection being based on intended non-use of the non-selected~~
~~ones;~~
coupling a plurality of cache memory devices and at least one passive
device to the first surface to form a multi-chip subassembly, wherein the at
least one passive device is selected from a group consisting of resistors,
capacitors, and inductors;
testing ~~said plurality of cache memory devices~~ only a portion of the selected ones of
the plurality of conductive pads on said interposer;
coupling said interposer to a substrate with the solder balls and coupling a
microprocessor device to the substrate after said testing if said plurality of cache memory
devices pass said testing; and

not coupling said interposer to the substrate and not coupling the microprocessor device to the interposer if said plurality of cache memory devices does not pass said testing .

20. (cancelled)

21. (previously amended) The method of claim 19 wherein the interposer comprises organic material.

22. (withdrawn) The method of claim 19 wherein coupling at least one semiconductor die comprises a C4 process.

23. (cancelled)

24. (withdrawn) The method of claim 19 further comprising coupling a single chip carrier to the substrate.

25. (withdrawn) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

26. (previously amended) The method of claim 19, further comprising:
creating a plurality of contacts on the substrate; and
electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.